MSKSEMI 美森科







TSS



MOV



GDT



PIFD

MM3ZXXX-MS

Product specification





FEATURES

- Total power dissipation: Max. 200mW.
- Wide zener reverse voltage range 2.0V to 75V.
- Small plastic package suitable for surface mounted design.
- Tolerance approximately±5%

MECHANICAL DATA

Case: SOD-323

 Terminals: Solderable per MIL-STD-750, Method 2026

Approx. Weight: 5.48mg / 0.00019oz

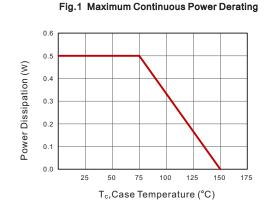
Reference News

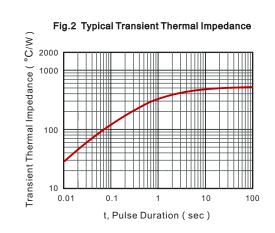
PACKAGE OUTLINE	PIN CONFIGURATION	
1. Cathode 2. Anode		
SOD-323		

Absolute Maximum Ratings And Characteristics (Ta = 25°C)

Parameter	Symbol	Value	Unit
Power Dissipation	P _{tot}	200	mW
Forward Voltage at I _F = 10 mA	V_{F}	0.9	V
Typical thermal resistance juncting to ambient ⁽¹⁾	Reja	417	°C/W
Operating and Storage Temperature Range	Tj, Tstg	-55 ~ +150	°C

(1) Thermal resistance from junction to ambient at P.C.B. mounted with 2.0" X 2.0" (54 X 5 cm) copper areas pads.







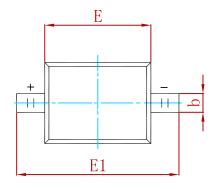
Characteristics at Ta = 25°C

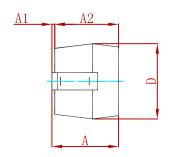
		Zener Voltage Range (1)			Dynamic Impedance	Reverse Current		
Type	Marking		VzT (at Iz	г)	IZT	ZzT (at I _{ZT})	lR	at V _R
		Min (V)	Nom (V)	Max (V)	(mA)	Max (Ω)	Max (µA)	(V)
MM3Z2V0-MS	B0	1.8	2.0	2.15	5	100	120	0.5
MM3Z2V2-MS	C0	2.08	2.2	2.33	5	100	120	0.7
MM3Z2V4-MS	1C	2.28	2.4	2.56	5	100	120	1
MM3Z2V7-MS	1D	2.5	2.7	2.9	5	110	120	1
MM3Z3V0-MS	1E	2.8	3.0	3.2	5	120	50	1
MM3Z3V3-MS	1F	3.1	3.3	3.5	5	130	20	1
MM3Z3V6-MS	1H	3.4	3.6	3.8	5	130	10	1
MM3Z3V9-MS	1J	3.7	3.9	4.1	5	130	5	1
MM3Z4V3-MS	1K	4	4.3	4.6	5	130	5	1
MM3Z4V7-MS	1M	4.4	4.7	5	5	130	2	1
MM3Z5V1-MS	1N	4.8	5.1	5.4	5	130	2	1.5
MM3Z5V6-MS	1P	5.2	5.6	6	5	80	1	2.5
MM3Z6V2-MS	1R	5.8	6.2	6.6	5	50	1	3
MM3Z6V8-MS	1X	6.4	6.8	7.2	5	30	0.5	3.5
MM3Z7V5-MS	1Y	7	7.5	7.9	5	30	0.5	4
MM3Z8V2-MS	1Z	7.7	8.2	8.7	5	30	0.5	5
MM3Z9V1-MS	2A	8.5	9.1	9.6	5	30	0.5	6
MM3Z10-MS	2B	9.4	10	10.6	5	30	0.1	7
MM3Z11-MS	2C	10.4	11	11.6	5	30	0.1	8
MM3Z12-MS	2D	11.4	12	12.7	5	35	0.1	9
MM3Z13-MS	2E	12.4	13	14.1	5	35	0.1	10
MM3Z15-MS	2F	13.8	15	15.6	5	40	0.1	11
MM3Z16-MS	2H	15.3	16	17.1	5	40	0.1	12
MM3Z18-MS	2J	16.8	18	19.1	5	45	0.1	13
MM3Z20-MS	2K	18.8	20	21.2	5	50	0.1	15
MM3Z22-MS	2M	20.8	22	23.3	5	55	0.1	17
MM3Z24-MS	2N	22.8	24	25.6	5	60	0.1	19
MM3Z27-MS	2P	25.1	27	28.9	2	70	0.1	21
MM3Z30-MS	2R	28	30	32	2	80	0.1	23
MM3Z33-MS	2X	31	33	35	2	80	0.1	25
MM3Z36-MS	2Y	34	36	38	2	90	0.1	27
MM3Z39-MS	2Z	37	39	41	2	100	0.1	30
MM3Z43-MS	3A	40	43	46	2	130	0.1	33
MM3Z47-MS	3B	44	47	50	2	150	0.1	36
MM3Z51-MS	3C	48	51	54	2	180	0.1	39
MM3Z56-MS	3D	52	56	60	2	200	0.1	43
MM3Z62-MS	3E	58	62	66	2	215	0.1	47
MM3Z68-MS	3F	64	68	72	2	240	0.1	52
MM3Z75-MS	3H	70	75	79	2	265	0.1	56

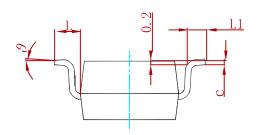
⁽¹⁾ V_{ZT} is tested with pulses (20 ms)



PACKAGE MECHANICAL DATA

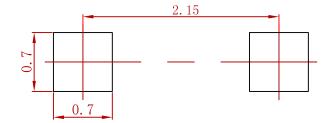






Cymahal	Dimensions	In Millimeters	Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
Α		1.000		0.039	
A1	0.000	0.100	0.000	0.004	
A2	0.800	0.900	0.031	0.035	
b	0.250	0.350	0.010	0.014	
С	0.080	0.150	0.003	0.006	
D	1.200	1.400	0.047	0.055	
E	1.600	1.800	0.063	0.071	
E1	2.550	2.750	0.100	0.108	
L,	0.475 REF.		0.019	REF.	
L1	0.250	0.400	0.010	0.016	
θ	0°	8°	0°	8°	

Suggested Pad Layout



Note:

- 1. Controlling dimension:in millimeters.
- 2.General tolerance:± 0.05mm.
- 3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
MM3ZXXX-MS	SOD-323	3000



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